S-543/03/01465 SK 281 Us

Docket No.: Q91465

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## DECLARATION AND POWER CHATTORNI GN PATENT APPLICATION (37 CFR 1.63)

As a below named inventor, I hereby declare that: My residence, mailing address, and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## CURING RESIN COMPOSITION, SEALING MATERIAL FOR LIQUID CRYSTAL DISPLAY DEVICE AND LIQUID CRYSTAL DISPLAY DEVICE

the application of which

is attached hereto	as P	vas filed on June 4, 2004 CT International Application Numb nfirmation No		
I hereby state that I have reviewed and by any amendment specifically referred		f the above identified application, in	ncluding the cla	ims, as amended
I acknowledge the duty to disclose continuation-in-part application(s), mat the national or PCT international filing	erial information which be	ecame available between the filing of	in 37 CFR 1.5 date of the prior	6, including for r application and
I hereby claim foreign priority under 3: breeder's rights certificate(s), or 365(a) United States of America, listed below inventor's or plant breeder's rights ce application on which priority is claimed	of any PCT international and have also identified rtificate(s), or any PCT in	application(s) which designated at below, by checking the box, any f	least one count oreign applicat	ry other than the ion(s) for patent,
Delta A. P. C. Namber(s)	Country	Filing Date	Priority Yes	Claimed No
Prior Application Number(s) 2003-159905	JP	June 04, 2003	<u></u>	
2003-159906	JP	June 04, 2003	☑	
2003-159909	JP	June 04, 2003	Ø	
2003-162774	JP	June 06, 2003	$\square$	
2003-165410	JP	June 10, 2003	☑	
2003-270397	JP	July 2, 2003	$\square$	
2003-279299	JP	July 24, 2003	✓	
2003-284115	JP	July 31, 2003	Ø	
2003-394614	JP	November 25, 2003	$\overline{\mathbf{v}}$	
2003-394615	JP	November 25, 2003	$\square$	
2003-394616	JP	November 25, 2003	☑	
2003-394617	JP	November 25, 2003	$\square$	
2003-394618	JP	November 25, 2003		

I hereby claim benefit under 35 United States Code §119(e) of any United States provisional application(s) listed below.

JP

Application Number(s)

2003-394619

Filing Date

November 25, 2003

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I hereby claim benefit under 35 United States Code §120 of any United States application(s) or §365(c) of any PCT International application(s) designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in a listed prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge my duty to disclose any information material to the patentability of this application as defined in 37 C.F.R. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. or International Application Number(s)

U.S. or International Filing Date

Status

I hereby appoint all attorneys of SUGHRUE MION, PLLC who are listed under the USPTO Customer Number shown below as my attorneys to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith, recognizing that the specific attorneys listed under that Customer Number may be changed from time to time at the sole discretion of Sughrue Mion, PLLC, and request that all correspondence about the application be addressed to the address filed under the same USPTO Customer Number.

WASHINGTON OFFICE

23373

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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